

EDAPS 2019

IEEE Electrical Design of Advanced Packaging and Systems

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<http://edaps.org>

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Call for Papers

The IEEE Electrical Design of Advanced Packaging and Systems (EDAPS) Symposium has been one of main events in South Asia and Asia Pacific design communities, which attracts world class designers and researchers to share their most recent results related to modeling, simulation, and electrical design issues at on-chip, package, and system/module levels. The symposium consists of tutorials, paper presentations, industry exhibition, workshops and poster presentations. The technical program of the symposium addresses the current technical issues facing design in IC, SiP/SoP packaging, EMI/EMC, RF isolation, and most importantly applications of AI in the next generation design of 3D IC (SoC, RF CMOS, RF SoC), FO/InFO PoPs, heterogeneous RF-passives systems, and EDA tools smart for Semiconductor (Silicon) IP.

Taiwan is famously known as Silicon Island, which has played a leading role in design, fabrication, and manufacturing services at chip, package, and board levels. Let's all participate this highly anticipated event where knowledge sharing and cordial exchanges between the academia and industry will surely take place.

Topics:

- 3D IC/3D Stacked IC, SI, PI, EMC systems, Measurement techniques, Systems (including 5G antennas and AI for design)
- AI-based electrical design for SoC, SiP, and Board designs
- Homogeneous RF CMOS and RF SoC designs
- Heterogeneous Integrated RF-passives systems (Front End) design for 5G Mobility
- Antennas for 5G, Integration of Security and AI chip

Manuscript Submission Deadline: Aug. 5, 2019

Notification of Acceptance: Sep. 20, 2019

Selected papers will be invited for publication in the IEEE Transactions on Components, Packaging and Manufacturing Technology.

Awards

Best Papers Award

Best Poster Papers Award

TPC Co-chair Hsin-Chia Lu, NTU

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Tutorial and Papers Submission

TPC chair Ding-Bing Lin, NTUST

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